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## STACK INFORMATION

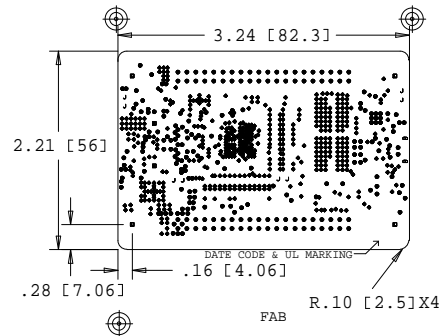
STACK INFORMATION				IMPEDANCE			
LAYERS	TYPE	THICKNESS(MILS)					
TOP SIDE SOLDER MASK			0.50MILS	SINGLE ENDED	OHM	DIFFERENTIAL	OHM
L1	TOP	COPPER+PLATING	1.30MILS	7.2MILS,50 OHM+/-10%	49.91 OHM	6.5/13/6.5 MILS,	95-99
L2	GND1	PREPREG	4.30 MILS				
		COPPER	0.65MILS				
L3	SIG1	CORE	4.00MILS				
		COPPER	0.65MILS	5MILS,50 OHM +/-10%	47.76 OHM		
L4	PWR1	PREPREG	9.50MILS				
		COPPER	0.65MILS				
L5	PWR2	CORE	18.0MILS				
		COPPER	0.65MILS				
L6	SIG2	PREPREG	9.50MILS				
		COPPER	0.65MILS	5MILS,50 OHM +/-10%	47.76 OHM		
L7	GND2	CORE	4.00MILS				
		COPPER	0.65MILS				
L8	BOTTOM	PREPREG	4.30MILS				
		COPPER+PLATING	1.30MILS	7.2MILS,50 OHM+/-10%	49.91 OHM	6.5/13/6.5 MILS,	95-99
BOTTOM SIDE SOLDER MASK			0.50 MILS	BOARD THICKNESS : 0.062" +/-0.006",MATERIAL 370HR			
TOTAL			61.10 MILS				
			1.55MM				

## REVISIONS


REV	DESCRIPTION	DATE	APPROVED
01	PROTO RELEASE	11/04/14	
02	UPDATED AS PER 630-60194-01 REV02 SCHEMATICS	15/05/14	
03	FIXED DFA ISSUES, NET ADDED FOR J7.4	09/06/14	
04	IMPLEMENTED SILKSCREEN AND FAB CHANGES	12/06/14	

## NOTES:(UNLESS OTHERWISE SPECIFIED)

1. ROHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
  2. MATERIAL:
    - A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
    - B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
    - C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION
  3. DRILLING:
    - A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/- .003 TOL. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
    - B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
  4. PLATING:
    - COPPER PLATING IN THRU-HOLES .001 min.
  5. MARKING:
    - A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
    - B.FABRICATOR TO PLACE DATE CODE AND UL LOGO ON SECONDARY SIDE IN SILKSCREEN
  6. FINAL FABRICATION:
    - A. SOLDERMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER..PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR \*\*BLUE\*\*
    - B. ALL VIAS THAT ARE PLACED ON EXPOSED PADS MUST BE PLUGGED WITH SOLDERMASK INK ON THE SIDE WHERE IT IS MASKED IN THE SOLDER MASK FILM.THIS IS TO AVOID SOLDER FLOW THROUGH VIA HOLE.
  7. FINISH:
    - A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
    - B. NICKEL THICKNESS. 100-200 MICROINCHES.
    - C. GOLD THICKNESS: 3-10 MICROINCHES.
  8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN SILKSCREEN ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V), DATE CODE (WWYY), AND ROHS COMPLIANT SYMBOL.
  9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
  - 10.MAXIMUM WARP OR TWIST SHALL NOT EXCEED 0.005" PER INCH
  - 11.TESTING:
    - A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED
    - B. T-LINE IMPEDANCE TO BE TESTED OR GURANTEED WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED
  - 12.MINIMUM TRACE WIDTH : 5 MILS  
MINIMUM SPACING : 4.1 MILS
  - 13.LAYER LADDER PROVIDED IN THE PCB SHOULD NOT BE MASKED
  - 14.DESIGN TEAM:
    - IN SOLDER MASK LAYER, COPPER PAD HAS BEEN ENABLED INSTEAD OF MASK PAD FOR PROVIDING 1:1 SOLDER MASK OPENING FOR PADS ALL OVER THE BOARD.
- CAM TEAM:  
PLS DELETE NOTE 14 DURING GERBER GENERATION



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	8.0	+3.0/-3.0	PLATED	224
•	10.0	+3.0/-3.0	PLATED	310
•	12.0	+3.0/-3.0	PLATED	151
•	30.0	+3.0/-3.0	PLATED	5
•	39.0	+3.0/-3.0	PLATED	4
•	40.0	+3.0/-3.0	PLATED	80
•	40.16	+3.0/-3.0	PLATED	2
•	43.0	+3.0/-3.0	PLATED	8
•	95.0	+3.0/-3.0	PLATED	2
•	118.0	+2.0/-2.0	NON-PLATED	4
•	50.24x26.62	+3.0/-3.0	PLATED	2

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON: ANGLES +/- 2 2 PL DECIMALS +/- .010 3 PL DECIMALS +/- .005 THIRD ANGLE PROJECTIONS		SIGNATURES DRAWN : VANAJA CHECKED : PRAJITH ENGRG : SHREESHA ISSUED	DATE 12/06/14 12/06/14 12/06/14	COMPANY:  <b>CYPRESS</b> PERFORM FABRICATION DRAWING SUPERSPEED EXPLORER KIT	198 CHAMPION COURT SAN JOSE, CA 95134 (408) 943-2600			
CYPRESS PROPRIETARY THIS DOCUMENT CONTAINS CONFIDENTIAL. PROPRIETARY INFORMATION THAT IS CYPRESS SEMICONDUCTOR PROPERTY DO NOT DISCLOSE TO OR DUPLICATE FOR OTHERS EXCEPT AS AUTHORIZED BY CYPRESS					SIZE C	FSCM NO	DWG NO 610-60190-01	REV 04
				SCALE: 1/1		SHEET 1 OF 1		

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